

**REMARKS**

Claims 1-6 are pending.

The Examiner has issued a restriction requirement. The Examiner has classified the claims as Group I, Claims 5 and 6, drawn to a semiconductor device, classified in class 257, subclass 737; and Group II, Claims 1-4 drawn to a method of making a semiconductor device, classified in class 438, subclass 613.

Applicants respectfully traverse the restriction requirement. Applicants elect Group I, specifically, claims 5 and 6.

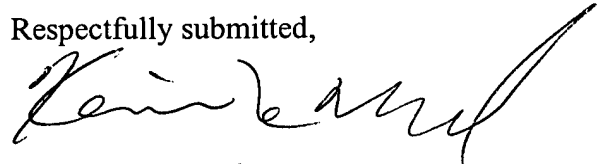
The Examiner states that the inventions are distinct because in the instant case, unpatentability of the Group I invention would not necessarily imply unpatentability of the process of the Group II invention since the device of group I could be made by the processes different from those of group II invention. The Examiner states that for example, "performing the steps in order of," and then recites the steps from claim 1. However, it is respectfully submitted that claim 1 does not require any particular order for performance of the steps, other than those that are practical or necessitated due to typical semiconductor manufacturing processes. Thus, it is respectfully submitted that any method used to manufacture a semiconductor device as recited in claims 5 and 6 would be covered by claim 1. Claim 1 recites providing a bumped die including a plurality of solder bumps thereon, providing a leadframe including source and gate connections, placing the bumped die on the leadframe such that the solder bumps contact the source and gate connections, providing a copper clip, attaching the copper clip to a backside of the bumped die with solder paste such that the copper clip contacts drain regions of the bumped die and a lead rail, and reflowing the solder paste and solder bumps. Thus, by "providing" the recited structure in claim 1 and coupling the structure with solder bumps and solder paste, the general process for making a semiconductor device as recited in claims 5 and 6 is presented.

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Accordingly, it is respectfully submitted that all claims are properly present in the present application and that the restriction requirement is improper. Accordingly, it is respectfully requested that the restriction requirement be withdrawn.

Respectfully submitted,



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